



Material Content Data Sheet



Sales Product Name		IFX7805ABTS		Issued		20. July 2018		
MA#		MA001060804						
Package		PG-TO220-3-1		Weight*		2067.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.237	0.06	0.06	599	599
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		118	
	non noble metal	iron	7439-89-6	0.816	0.04		395	
	non noble metal	copper	7440-50-8	815.335	39.45	39.50	394377	394890
	non noble metal	aluminium	7429-90-5	0.169	0.01	0.01	82	82
wire	non noble metal	aluminium	7429-90-5	0.169	0.01	0.01	82	82
encapsulation	organic material	carbon black	1333-86-4	1.272	0.06		615	
	plastics	epoxy resin	-	58.518	2.83		28305	
	inorganic material	silicondioxide	60676-86-0	576.275	27.87	30.76	278744	307664
leadfinish	non noble metal	tin	7440-31-5	21.462	1.04	1.04	10381	10381
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	118	119
solder	non noble metal	tin	7440-31-5	0.032	0.00		15	
	noble metal	silver	7440-22-4	0.040	0.00		19	
	non noble metal	lead	7439-92-1	1.517	0.07	0.07	734	768
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		86	
	non noble metal	iron	7439-89-6	0.590	0.03		286	
	non noble metal	copper	7440-50-8	589.466	28.51	28.55	285125	285497
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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